



# VN920DSP

## HIGH SIDE DRIVER

TYPE	$R_{DS(on)}$	$I_{OUT}$	$V_{CC}$
VN920DSP	16 m $\Omega$	25 A	36 V

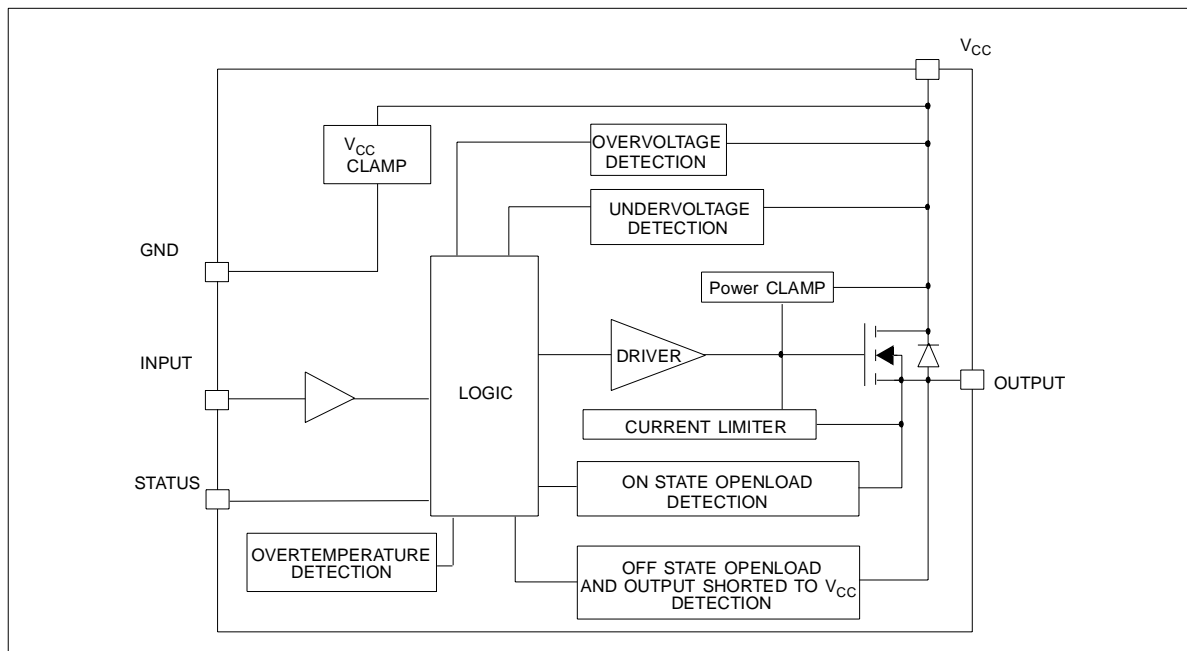
- CMOS COMPATIBLE INPUT
- ON STATE OPEN LOAD DETECTION
- OFF STATE OPEN LOAD DETECTION
- SHORTED LOAD PROTECTION
- UNDERVOLTAGE AND OVERVOLTAGE SHUTDOWN
- PROTECTION AGAINST LOSS OF GROUND
- VERY LOW STAND-BY CURRENT
- REVERSE BATTERY PROTECTION (\*)

### DESCRIPTION

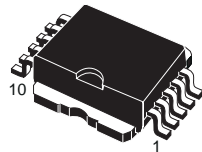
The VN920DSP is a monolithic device made by using STMicroelectronics VIPower M0-3 Technology, intended for driving any kind of load with one side connected to ground.

Active  $V_{CC}$  pin voltage clamp protects the device against low energy spikes (see ISO7637 transient compatibility table). Active current limitation

### BLOCK DIAGRAM



(\*) See application schematic at page 8



**PowerSO-10™**

ORDER CODES		
PACKAGE	TUBE	T&R
PowerSO-10™	VN920DSP	VN920DSP13TR

combined with thermal shutdown and automatic restart protect the device against overload.

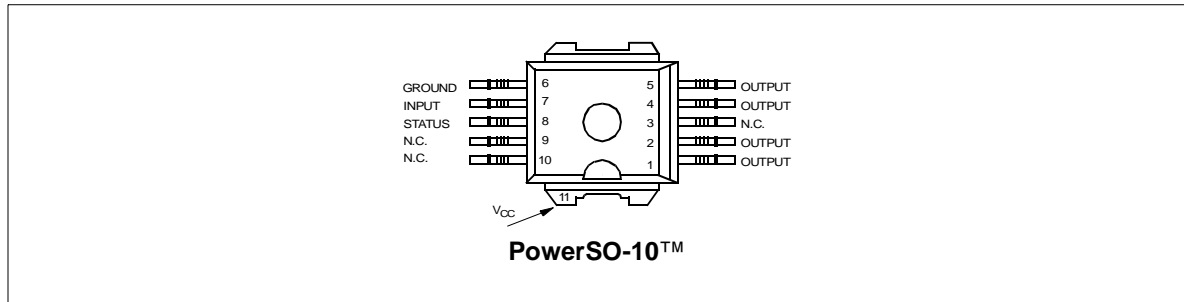
The device detects open load condition both is on and off state. Output shorted to  $V_{CC}$  is detected in the off state. Device automatically turns off in case of ground pin disconnection.

# VN920DSP

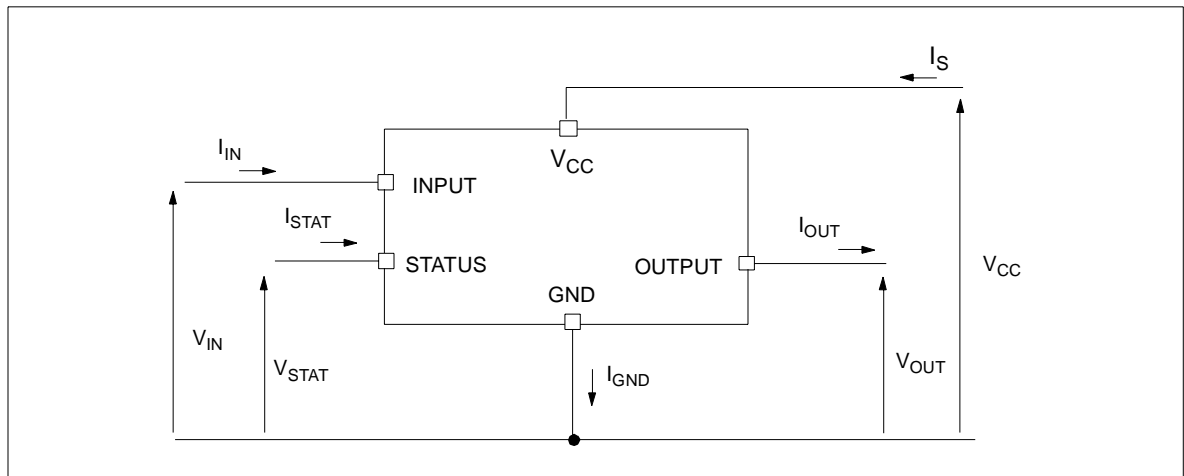
## ABSOLUTE MAXIMUM RATING

Symbol	Parameter	Value	Unit
$V_{CC}$	DC Supply Voltage	41	V
$-V_{CC}$	Reverse DC Supply Voltage	- 0.3	V
$-I_{GND}$	DC Reverse Ground Pin Current	- 200	mA
$I_{OUT}$	DC Output Current	Internally Limited	A
$-I_{OUT}$	Reverse DC Output Current	- 25	A
$I_{IN}$	DC Input Current	+/- 10	mA
$I_{STAT}$	DC Status Current	+/- 10	mA
$V_{ESD}$	Electrostatic Discharge (Human Body Model: R=1.5K $\Omega$ ; C=100pF)		
	- INPUT	4000	V
	- CURRENT SENSE	4000	V
	- OUTPUT	5000	V
	- $V_{CC}$	5000	V
$E_{MAX}$	Maximum Switching Energy (L=0.25mH; R <sub>L</sub> =0 $\Omega$ ; V <sub>bat</sub> =13.5V; T <sub>jstart</sub> =150 $^{\circ}$ C; I <sub>L</sub> =45A)	362	mJ
$P_{tot}$	Power Dissipation T <sub>C</sub> =25 $^{\circ}$ C	96.1	W
$T_j$	Junction Operating Temperature	Internally Limited	$^{\circ}$ C
$T_C$	Case Operating Temperature	- 40 to 150	$^{\circ}$ C
$T_{stg}$	Storage Temperature	- 55 to 150	$^{\circ}$ C

## CONNECTION DIAGRAM (TOP VIEW)



## CURRENT AND VOLTAGE CONVENTIONS



## THERMAL DATA

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal Resistance Junction-case	Max 1.3	°C/W
$R_{thj-amb}$	Thermal Resistance Junction-ambient	Max 51.3 (*)	°C/W

(\*) When mounted on a standard single-sided FR-4 board with 0.5cm<sup>2</sup> of Cu (at least 35µm thick).

ELECTRICAL CHARACTERISTICS (8V < V<sub>CC</sub> < 36V; -40°C < T<sub>j</sub> < 150°C unless otherwise specified)

## POWER

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
V <sub>CC</sub>	Operating Supply Voltage		5.5	13	36	V
V <sub>USD</sub>	Undervoltage Shut-down		3	4	5.5	V
V <sub>USDhyst</sub>	Undervoltage Shut-down hysteresis			0.5		V
V <sub>OV</sub>	Overvoltage Shut-down		36			V
R <sub>ON</sub>	On State Resistance	I <sub>OUT</sub> =10A; T <sub>j</sub> =25°C I <sub>OUT</sub> =10A I <sub>OUT</sub> =3A; V <sub>CC</sub> =6V			16 30 50	mΩ mΩ mΩ
I <sub>S</sub>	Supply Current	Off State; V <sub>CC</sub> =13V; V <sub>IN</sub> =V <sub>OUT</sub> =0V Off State; V <sub>CC</sub> =13V; V <sub>IN</sub> =V <sub>OUT</sub> =0V; T <sub>j</sub> =25°C On State; V <sub>CC</sub> =13V; V <sub>IN</sub> =5V; I <sub>OUT</sub> =0A		10 10	25 20 5	µA µA mA
I <sub>L(off1)</sub>	Off State Output Current	V <sub>IN</sub> =V <sub>OUT</sub> =0V	0		50	µA
I <sub>L(off2)</sub>	Off State Output Current	V <sub>IN</sub> =0V; V <sub>OUT</sub> =3.5V	-75		0	µA
I <sub>L(off3)</sub>	Off State Output Current	V <sub>IN</sub> =V <sub>OUT</sub> =0V; V <sub>CC</sub> =13V; T <sub>j</sub> =125°C			5	µA
I <sub>L(off4)</sub>	Off State Output Current	V <sub>IN</sub> =V <sub>OUT</sub> =0V; V <sub>CC</sub> =13V; T <sub>j</sub> =25°C			3	µA

SWITCHING (V<sub>CC</sub>=13V)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
t <sub>d(on)</sub>	Turn-on Delay Time	R <sub>L</sub> =1.3Ω		50		µs
t <sub>d(off)</sub>	Turn-off Delay Time	R <sub>L</sub> =1.3Ω		50		µs
dV <sub>OUT</sub> /dt <sub>(on)</sub>	Turn-on Voltage Slope	R <sub>L</sub> =1.3Ω		See relative diagram		V/µs
dV <sub>OUT</sub> /dt <sub>(off)</sub>	Turn-off Voltage Slope	R <sub>L</sub> =1.3Ω		See relative diagram		V/µs

## INPUT PIN

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
V <sub>IL</sub>	Input Low Level				1.25	V
I <sub>IL</sub>	Low Level Input Current	V <sub>IN</sub> =1.25V	1			µA
V <sub>IH</sub>	Input High Level		3.25			V
I <sub>IH</sub>	High Level Input Current	V <sub>IN</sub> =3.25V			10	µA
V <sub>I(hyst)</sub>	Input Hysteresis Voltage		0.5			V
V <sub>ICL</sub>	Input Clamp Voltage	I <sub>IN</sub> =1mA I <sub>IN</sub> =-1mA	6	6.8 -0.7	8	V V

## VN920DSP

### ELECTRICAL CHARACTERISTICS (continued)

#### STATUS PIN

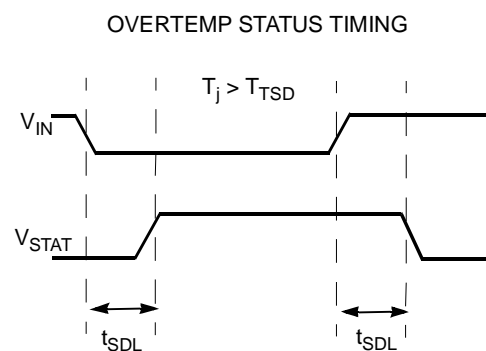
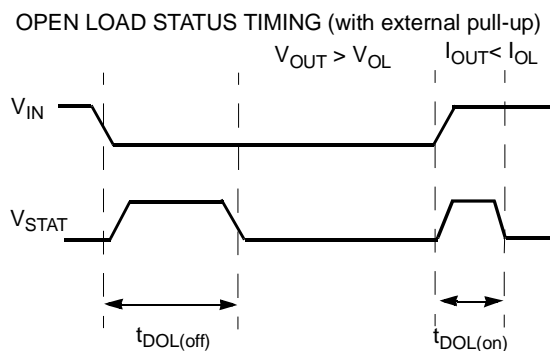
Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
$V_{STAT}$	Status Low Output Voltage	$I_{STAT}=1.6mA$			0.5	V
$I_{LSTAT}$	Status Leakage Current	Normal Operation $V_{STAT}=5V$			10	$\mu A$
$C_{STAT}$	Status Pin Input Capacitance	Normal Operation $V_{STAT}=5V$			100	pF
$V_{SCL}$	Status Clamp Voltage	$I_{STAT}=1mA$	6	6.8	8	V
		$I_{STAT}=-1mA$		-0.7		V

#### PROTECTIONS

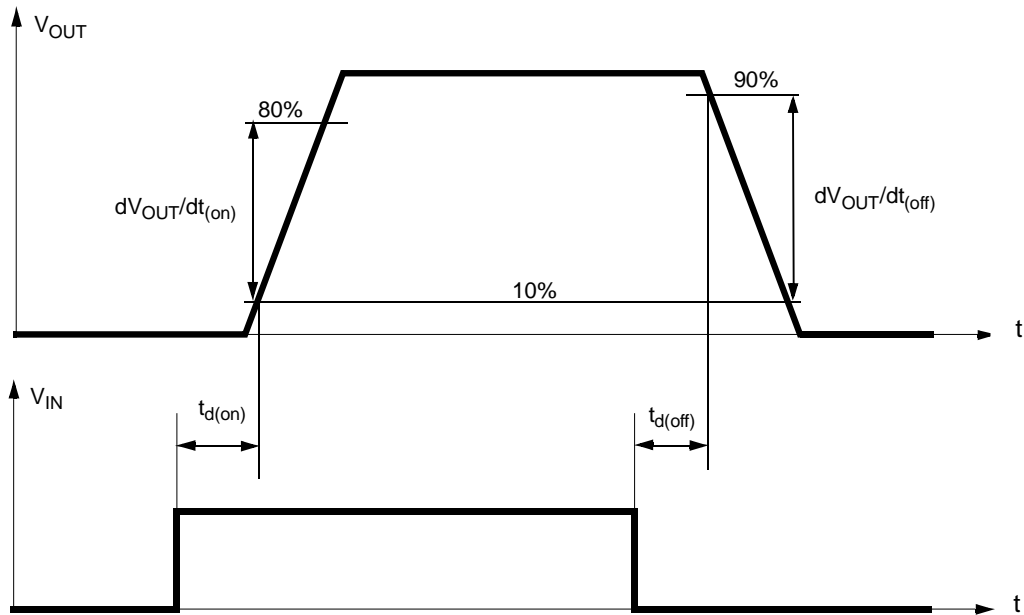
Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
$T_{TSD}$	Shut-down Temperature		150	175	200	$^{\circ}C$
$T_R$	Reset Temperature		135			$^{\circ}C$
$T_{hyst}$	Thermal Hysteresis		7	15		$^{\circ}C$
$t_{SDL}$	Status delay in overload condition	$T_j > T_{TSD}$			20	$\mu s$
$I_{lim}$	Current limitation	$5.5V < V_{CC} < 36V$	30	45	75	A
$V_{demag}$	Turn-off Output Clamp Voltage	$I_{OUT}=2A; V_{IN}=0V; L=6mH$	$V_{CC}-41$	$V_{CC}-48$	$V_{CC}-55$	V

#### OPENLOAD DETECTION

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
$I_{OL}$	Openload ON State Detection Threshold	$V_{IN}=5V$	300	500	700	mA
$t_{DOL(on)}$	Openload ON State Detection Delay	$I_{OUT}=0A$			200	$\mu s$
$V_{OL}$	Openload OFF State Voltage Detection Threshold	$V_{IN}=0V$	1.5	2.5	3.5	V
$t_{DOL(off)}$	Openload Detection Delay at Turn Off				1000	$\mu s$



## Switching time Waveforms



## TRUTH TABLE

CONDITIONS	INPUT	OUTPUT	STATUS
Normal Operation	L	L	H
	H	H	H
Current Limitation	L	L	H
	H	X	$(T_j < T_{TSD})$ H
	H	X	$(T_j > T_{TSD})$ L
Overtemperature	L	L	H
	H	L	L
Undervoltage	L	L	X
	H	L	X
Overvoltage	L	L	H
	H	L	H
Output Voltage $> V_{OL}$	L	H	L
	H	H	H
Output Current $< I_{OL}$	L	L	H
	H	H	L

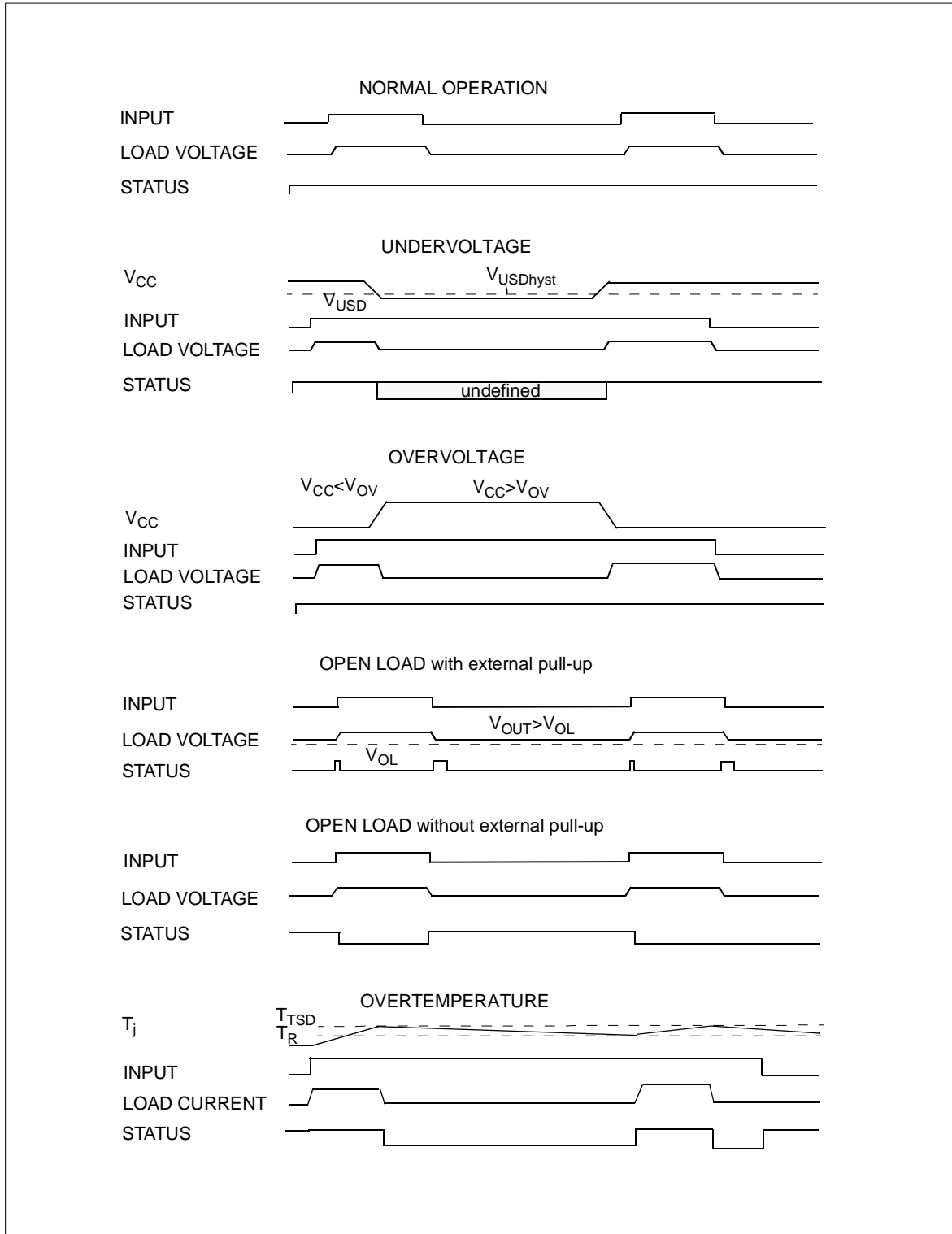
**ELECTRICAL TRANSIENT REQUIREMENTS ON V<sub>CC</sub> PIN**

ISO T/R 7637/1 Test Pulse	TEST LEVELS				Delays and Impedance
	I	II	III	IV	
1	-25 V	-50 V	-75 V	-100 V	2 ms 10 Ω
2	+25 V	+50 V	+75 V	+100 V	0.2 ms 10 Ω
3a	-25 V	-50 V	-100 V	-150 V	0.1 μs 50 Ω
3b	+25 V	+50 V	+75 V	+100 V	0.1 μs 50 Ω
4	-4 V	-5 V	-6 V	-7 V	100 ms, 0.01 Ω
5	+26.5 V	+46.5 V	+66.5 V	+86.5 V	400 ms, 2 Ω

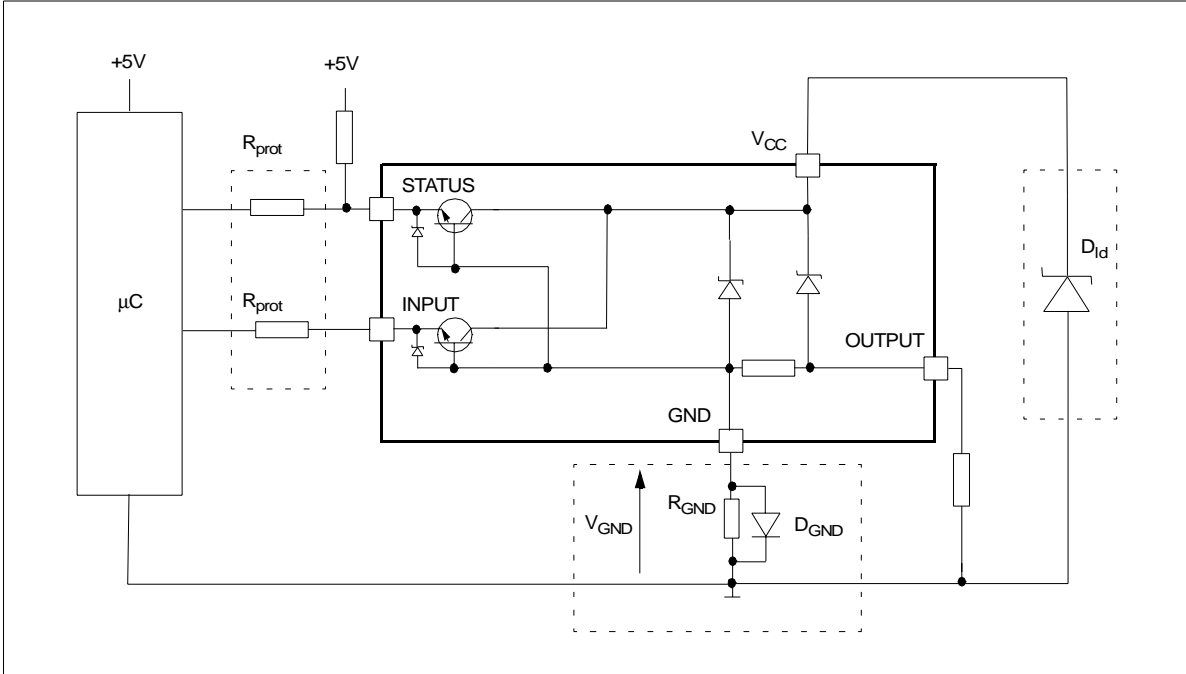
ISO T/R 7637/1 Test Pulse	TEST LEVELS RESULTS			
	I	II	III	IV
1	C	C	C	C
2	C	C	C	C
3a	C	C	C	C
3b	C	C	C	C
4	C	C	C	C
5	C	E	E	E

CLASS	CONTENTS
<b>C</b>	All functions of the device are performed as designed after exposure to disturbance.
<b>E</b>	One or more functions of the device is not performed as designed after exposure to disturbance and cannot be returned to proper operation without replacing the device.

Figure1: Waveforms



APPLICATION SCHEMATIC



**GND PROTECTION NETWORK AGAINST REVERSE BATTERY**

**Solution 1:** Resistor in the ground line (R<sub>GND</sub> only). This can be used with any type of load.

The following is an indication on how to dimension the R<sub>GND</sub> resistor.

- 1)  $R_{GND} \leq 600mV / (I_{S(on)max})$ .
- 2)  $R_{GND} \geq (-V_{CC}) / (-I_{GND})$

where -I<sub>GND</sub> is the DC reverse ground pin current and can be found in the absolute maximum rating section of the of the device's datasheet.

Power Dissipation in R<sub>GND</sub> (when V<sub>CC</sub><0: during reverse battery situations) is:

$$P_D = (-V_{CC})^2 / R_{GND}$$

This resistor can be shared amongst several different HSD. Please note that the value of this resistor should be calculated with formula (1) where I<sub>S(on)max</sub> becomes the sum of the maximum on-state currents of the different devices.

Please note that if the microprocessor ground is not common with the device ground then the R<sub>GND</sub> will produce a shift (I<sub>S(on)max</sub> \* R<sub>GND</sub>) in the input thresholds and the status output values. This shift will vary depending on many devices are ON in the case of several high side drivers sharing the same R<sub>GND</sub>.

If the calculated power dissipation leads to a large resistor or several devices have to share the same resistor then the ST suggest to utilize Solution 2 (see below).

**Solution 2:** A diode (D<sub>GND</sub>) in the ground line.

A resistor (R<sub>GND</sub>=1kΩ) should be inserted in parallel to D<sub>GND</sub> if the device will be driving an inductive load.

This small signal diode can be safely shared amongst several different HSD. Also in this case, the presence of the ground network will produce a shift (≈600mV) in the input threshold and the status output values if the microprocessor ground is not common with the device ground. This shift will not vary if more than one HSD shares the same diode/resistor network.

**LOAD DUMP PROTECTION**

D<sub>Id</sub> is necessary (Voltage Transient Suppressor) if the load dump peak voltage exceeds V<sub>CC</sub> max DC rating. The same applies if the device will be subject to transients on the V<sub>CC</sub> line that are greater than the ones shown in the ISO T/R 7637/1 table.

**µC I/Os PROTECTION:**

If a ground protection network is used and negative transient are present on the V<sub>CC</sub> line, the control pins will be pulled negative. ST suggests to insert a resistor (R<sub>prot</sub>) in line to prevent the µC I/Os pins to latch-up.

The value of these resistors is a compromise between the leakage current of µC and the current required by the HSD I/Os (Input levels compatibility) with the latch-up limit of µC I/Os.

$$-V_{CCpeak} / I_{latchup} \leq R_{prot} \leq (V_{OHµC} - V_{IH} - V_{GND}) / I_{IHmax}$$

Calculation example:

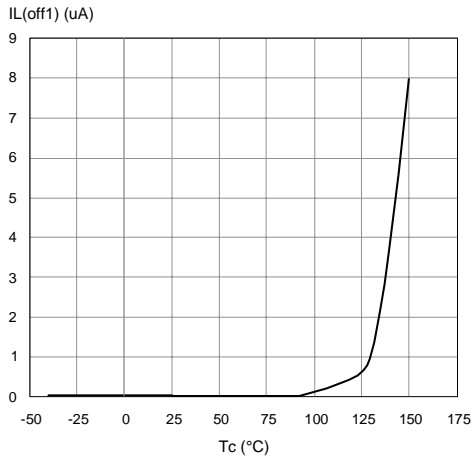
For V<sub>CCpeak</sub>= - 100V and I<sub>latchup</sub> ≥ 20mA; V<sub>OHµC</sub> ≥ 4.5V

$$5k\Omega \leq R_{prot} \leq 65k\Omega$$

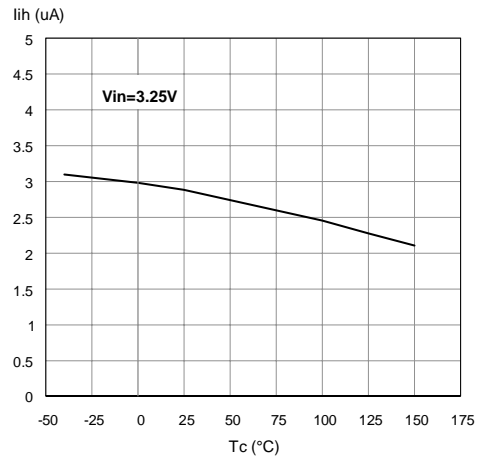
Recommended R<sub>prot</sub> value is 10kΩ.



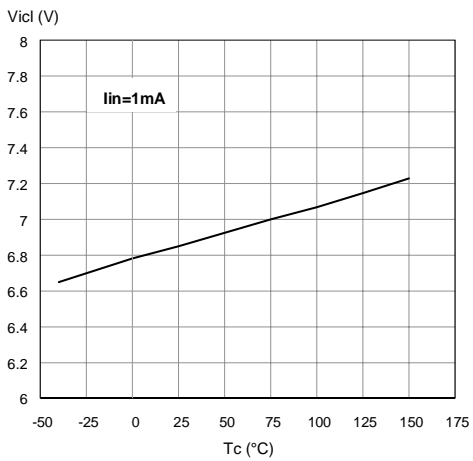
Off State Output Current



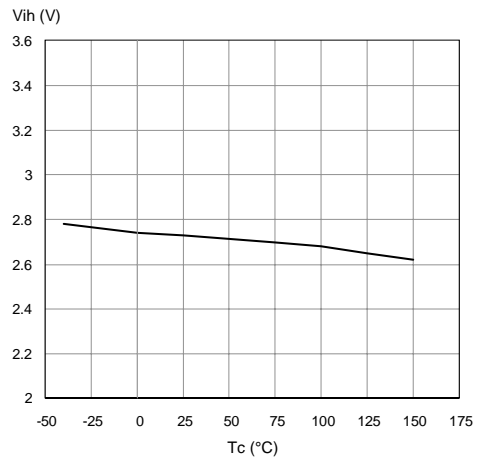
High Level Input Current



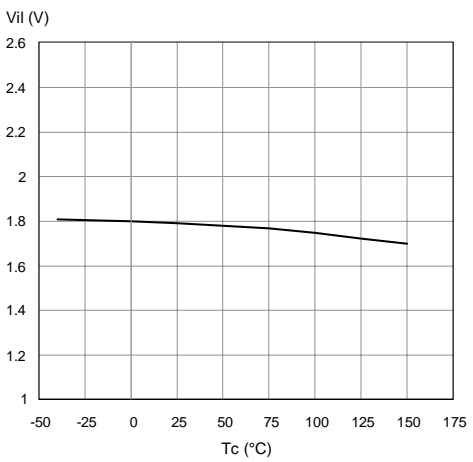
Input Clamp Voltage



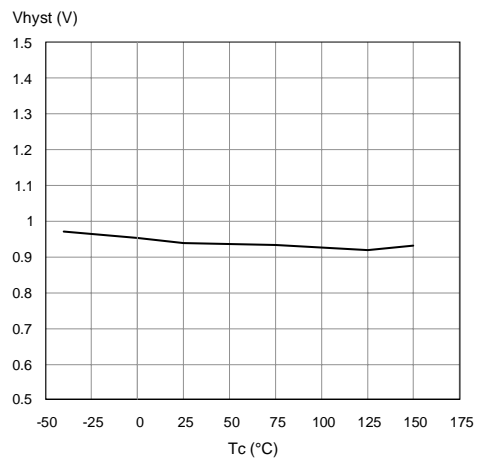
Input High Level



Input Low Level

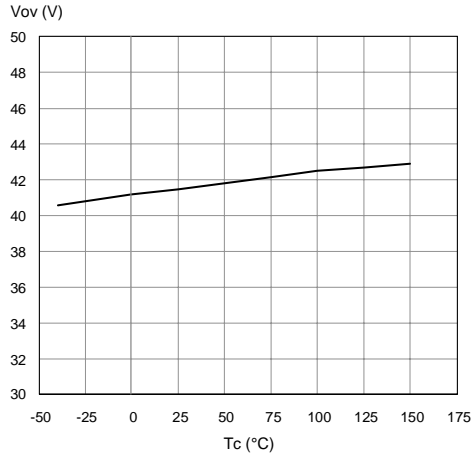


Input Hysteresis Voltage

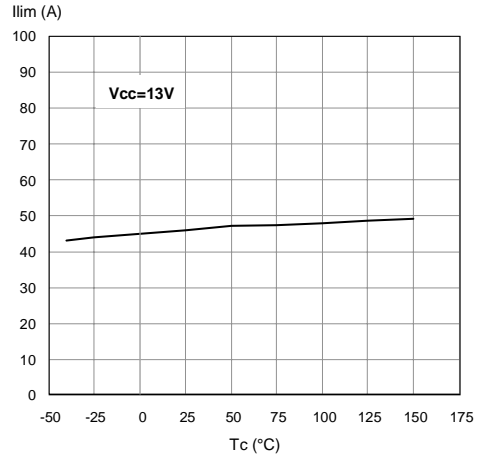


# VN920DSP

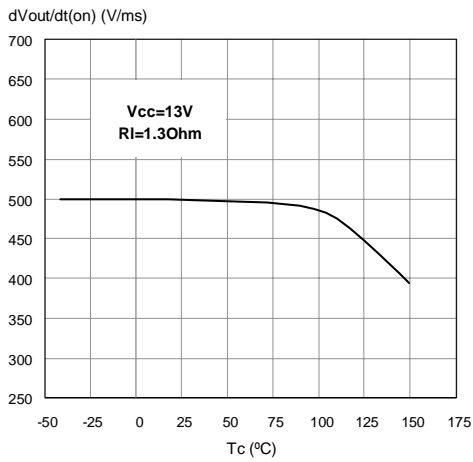
## Overvoltage Shutdown



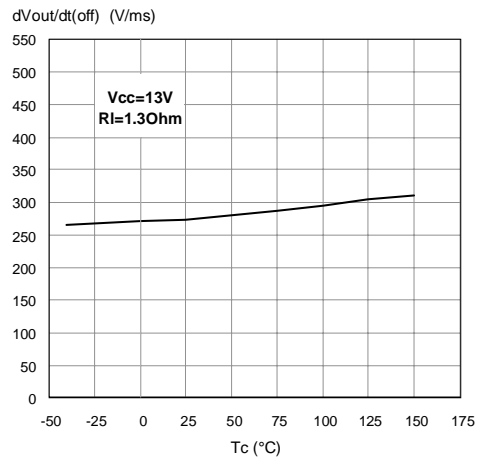
## I<sub>LIM</sub> Vs T<sub>case</sub>



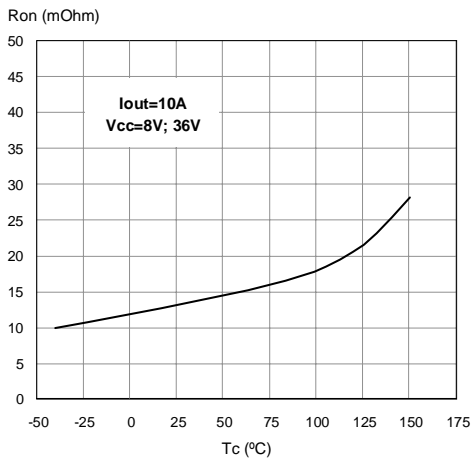
## Turn-on Voltage Slope



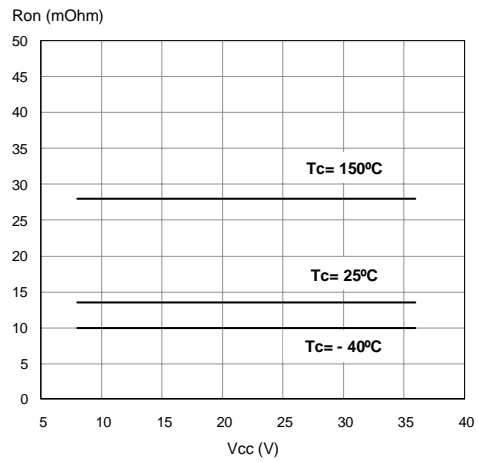
## Turn-off Voltage Slope



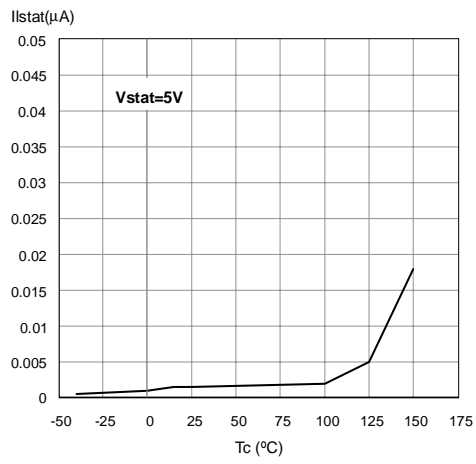
## On State Resistance Vs T<sub>case</sub>



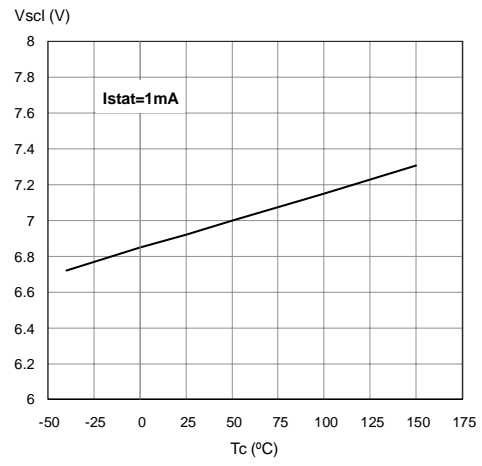
## On State Resistance Vs V<sub>CC</sub>



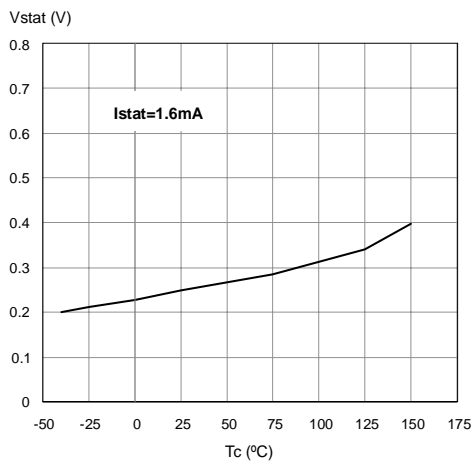
Status Leakage Current



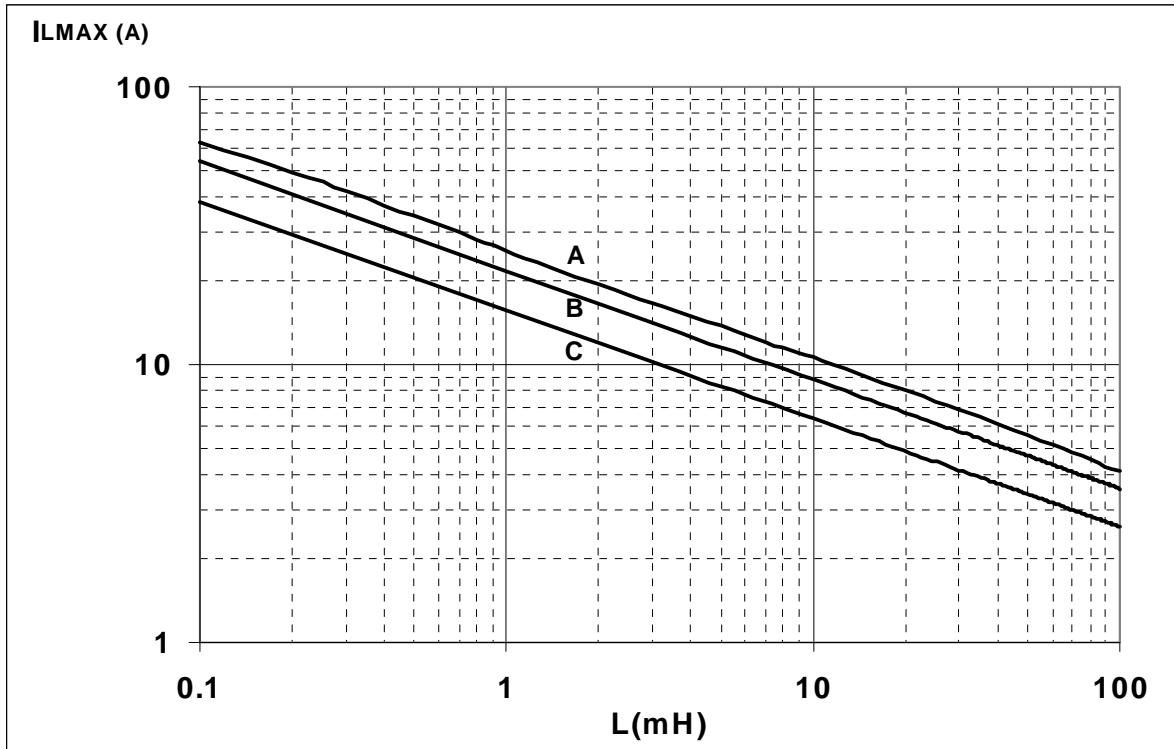
Status Clamp Voltage



Status Low Output Voltage



Maximum turn off current versus load inductance



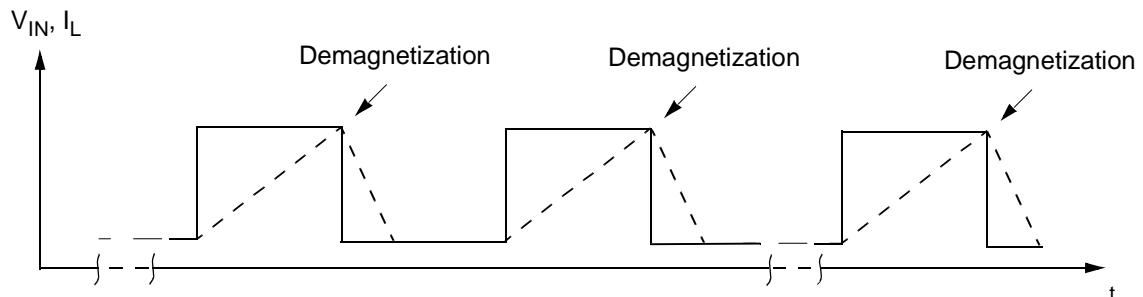
- A = Single Pulse at  $T_{Jstart}=150^{\circ}C$
- B= Repetitive pulse at  $T_{Jstart}=100^{\circ}C$
- C= Repetitive Pulse at  $T_{Jstart}=125^{\circ}C$

Conditions:

$V_{CC}=13.5V$

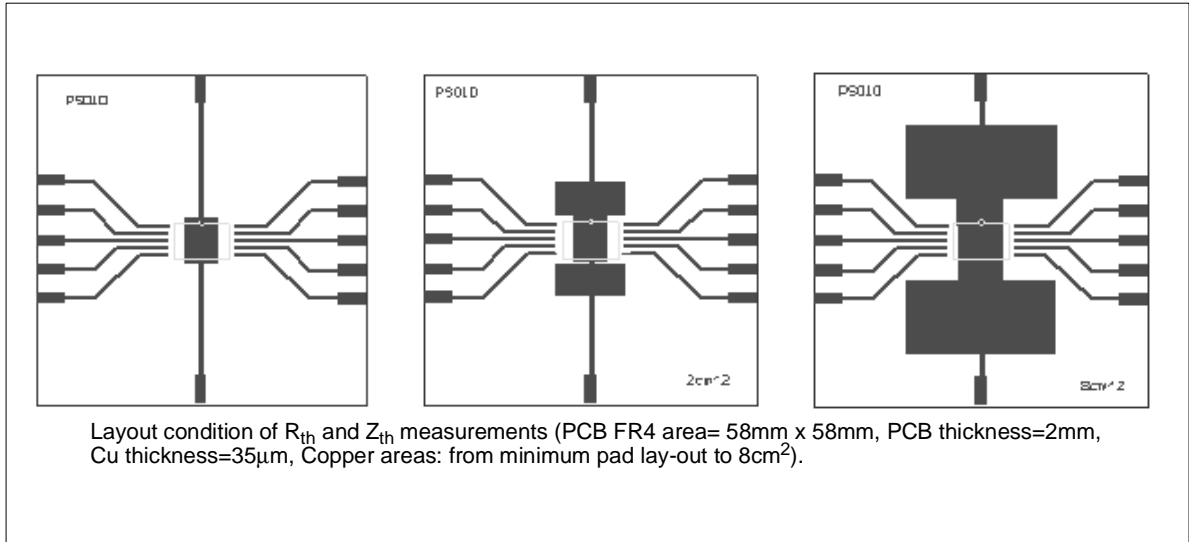
Values are generated with  $R_L=0\Omega$

In case of repetitive pulses,  $T_{Jstart}$  (at beginning of each demagnetization) of every pulse must not exceed the temperature specified above for curves B and C.

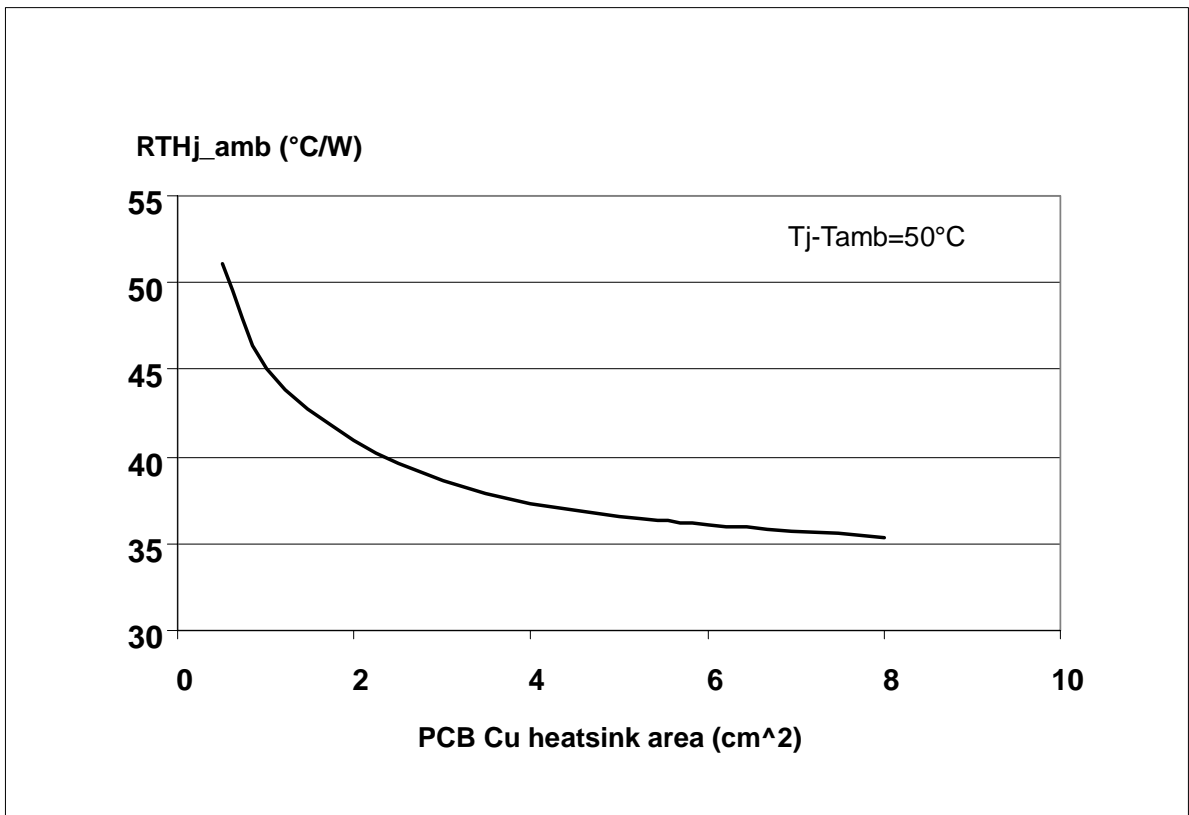


**PowerSO-10™ THERMAL DATA**

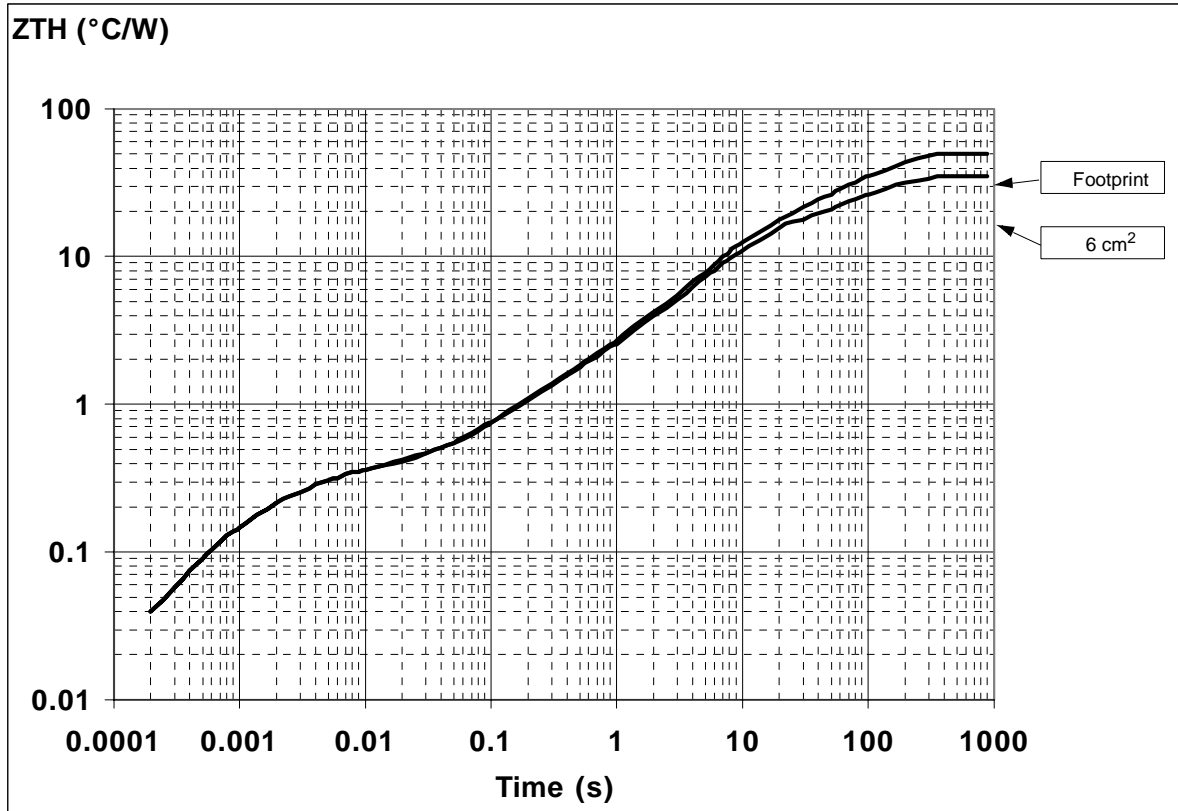
**PowerSO-10™ PC Board**



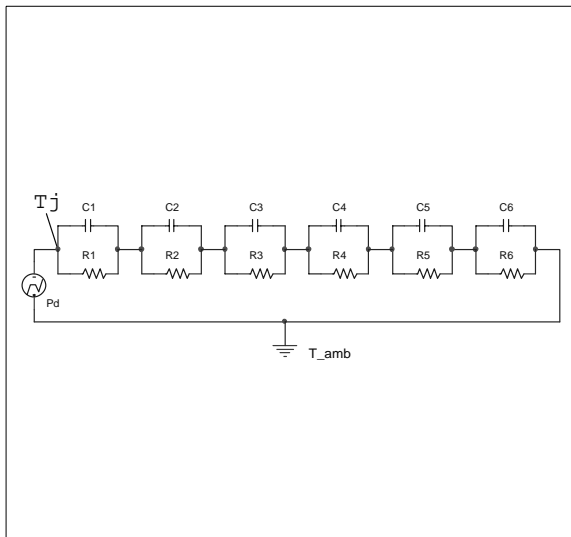
**$R_{thj-amb}$  Vs PCB copper area in open box free air condition**



PowerSO-10 Thermal Impedance Junction Ambient Single Pulse



Thermal fitting model of a single channel HSD in PowerSO-10



Pulse calculation formula

$$Z_{TH\delta} = R_{TH} \cdot \delta + Z_{THtp}(1 - \delta)$$

where  $\delta = t_p/T$

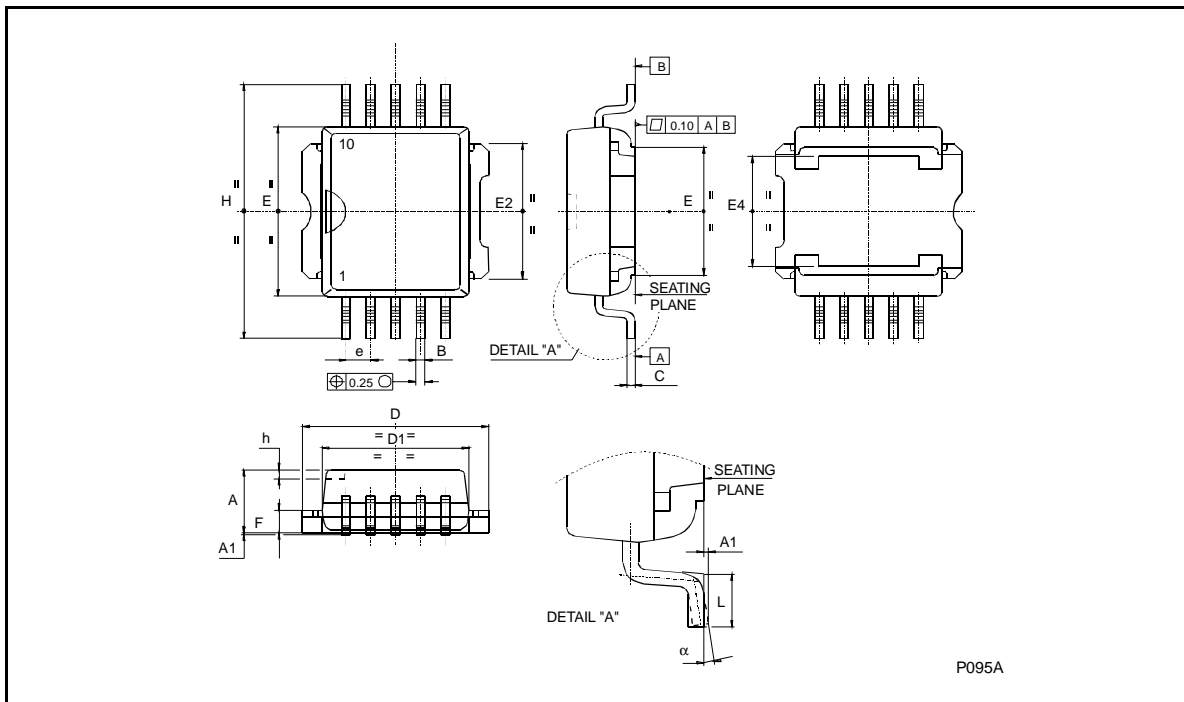
Thermal Parameter

Area/island (cm <sup>2</sup> )	Footprint	6
R1 (°C/W)	0.02	
R2 (°C/W)	0.1	
R3 (°C/W)	0.2	
R4 (°C/W)	0.8	
R5 (°C/W)	12	
R6 (°C/W)	37	22
C1 (W.s/°C)	0.0015	
C2 (W.s/°C)	7.00E-03	
C3 (W.s/°C)	0.015	
C4 (W.s/°C)	0.3	
C5 (W.s/°C)	0.75	
C6 (W.s/°C)	3	5

**PowerSO-10™ MECHANICAL DATA**

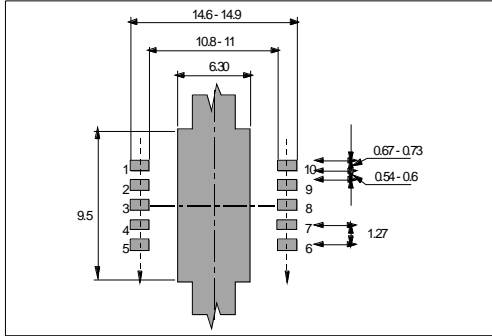
DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	3.35		3.65	0.132		0.144
A (*)	3.4		3.6	0.134		0.142
A1	0.00		0.10	0.000		0.004
B	0.40		0.60	0.016		0.024
B (*)	0.37		0.53	0.014		0.021
C	0.35		0.55	0.013		0.022
C (*)	0.23		0.32	0.009		0.0126
D	9.40		9.60	0.370		0.378
D1	7.40		7.60	0.291		0.300
E	9.30		9.50	0.366		0.374
E2	7.20		7.60	0.283		300
E2 (*)	7.30		7.50	0.287		0.295
E4	5.90		6.10	0.232		0.240
E4 (*)	5.90		6.30	0.232		0.248
e		1.27			0.050	
F	1.25		1.35	0.049		0.053
F (*)	1.20		1.40	0.047		0.055
H	13.80		14.40	0.543		0.567
H (*)	13.85		14.35	0.545		0.565
h		0.50			0.002	
L	1.20		1.80	0.047		0.070
L (*)	0.80		1.10	0.031		0.043
α	0°		8°	0°		8°
α (*)	2°		8°	2°		8°

(\*) Muar only POA P013P



# VN920DSP

## PowerSO-10™ SUGGESTED PAD LAYOUT



## TUBE SHIPMENT (no suffix)

**CASABLANCA**

**MUAR**

All dimensions are in mm.

	Base Q.ty	Bulk Q.ty	Tube length (±0.5)	A	B	C (±0.1)
<b>Casablanca</b>	50	1000	532	10.4	16.4	0.8
<b>Muar</b>	50	1000	532	4.9	17.2	0.8

## TAPE AND REEL SHIPMENT (suffix "13TR")

### REEL DIMENSIONS

Base Q.ty	600
Bulk Q.ty	600
A (max)	330
B (min)	1.5
C (±0.2)	13
F	20.2
G (+2 / -0)	24.4
N (min)	60
T (max)	30.4

All dimensions are in mm.

### TAPE DIMENSIONS

According to Electronic Industries Association (EIA) Standard 481 rev. A, Feb 1986

Parameter	Symbol	Value
Tape width	W	24
Tape Hole Spacing	P0 (±0.1)	4
Component Spacing	P	24
Hole Diameter	D (±0.1/-0)	1.5
Hole Diameter	D1 (min)	1.5
Hole Position	F (±0.05)	11.5
Compartment Depth	K (max)	6.5
Hole Spacing	P1 (±0.1)	2



Information furnished is believed to be accurate and reliable. However, STMicroelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of STMicroelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. STMicroelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of STMicroelectronics. The ST logo is a trademark of STMicroelectronics

© 2002 STMicroelectronics - Printed in ITALY- All Rights Reserved.

STMicroelectronics GROUP OF COMPANIES

Australia - Brazil - Canada - China - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia -  
Malta - Morocco - Singapore - Spain - Sweden - Switzerland - United Kingdom - U.S.A.

<http://www.st.com>